

L Number	Hits	Search Text	DB	Time stamp
1	8713	118/715.ccls. or 118/728.ccls. or 118/50.ccls. or 156/345.29.ccls. or 156/345.33.ccls. or 156/345.34.ccls. or 156/345.35.ccls. or 156/345.36.ccls. or 156/345.26.ccls. or 156/345.51.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/29 11:26
2	8041	137/262-264.ccls. or 137/454.2 or 137/560.ccls. or 137/561r.ccls. or 137/561a.ccls. or 137/571-576.ccls. or 137/590.ccls. or 137/594-596.ccls. or 137/599.01.ccls. or 137/599.05-599.07.ccls. or 137/602.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/29 11:26
3	2281	141/285-286.ccls. or 141/37.ccls. or 141/44-47.ccls. or 141/54.ccls. or 141/301-302.ccls. or 141/367.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/29 11:26
4	457	261/127.ccls. or 261/131.ccls. or 261/146-147.ccls. or 261/150.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/29 11:26
5	2575	261/19-22.ccls. or 261/23.1.ccls. or 261/40.ccls. or 261/42.ccls. or 261/62-63.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/29 11:26
6	7030	261/64.1.ccls. or 261/65.ccls. or 261/75-76.ccls. or 261/94-96.ccls. or 261/100-102.ccls. or 261/105.ccls. or 261/108-109.ccls. or 261/113.ccls. or 261/114.1.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/29 11:26
8	28445	(118/715.ccls. or 118/728.ccls. or 118/50.ccls. or 156/345.29.ccls. or 156/345.33.ccls. or 156/345.34.ccls. or 156/345.35.ccls. or 156/345.36.ccls. or 156/345.26.ccls. or 156/345.51.ccls.) or (137/262-264.ccls. or 137/454.2 or 137/560.ccls. or 137/561r.ccls. or 137/561a.ccls. or 137/571-576.ccls. or 137/590.ccls. or 137/594-596.ccls. or 137/599.01.ccls. or 137/599.05-599.07.ccls. or 137/602.ccls.) or (141/285-286.ccls. or 141/37.ccls. or 141/44-47.ccls. or 141/54.ccls. or 141/301-302.ccls. or 141/367.ccls.) or (261/127.ccls. or 261/131.ccls. or 261/146-147.ccls. or 261/150.ccls.) or (261/19-22.ccls. or 261/23.1.ccls. or 261/40.ccls. or 261/42.ccls. or 261/62-63.ccls.) or (261/64.1.ccls. or 261/65.ccls. or 261/75-76.ccls. or 261/94-96.ccls. or 261/100-102.ccls. or 261/105.ccls. or 261/108-109.ccls. or 261/113.ccls. or 261/114.1.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/29 11:26

14	4703	(wafer or substrate) and (((injector or nozzle or sprayer or port or jet or "shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) with gas)) and ((heat or thermal) with (stress or strain)) not (((118/715.ccls. or 118/728.ccls. or 118/50.ccls. or 156/345.29.ccls. or 156/345.33.ccls. or 156/345.34.ccls. or 156/345.35.ccls. or 156/345.36.ccls. or 156/345.26.ccls. or 156/345.51.ccls.) or (137/262-264.ccls. or 137/454.2 or 137/560.ccls. or 137/561.ccls. or 137/561a.ccls. or 137/571-576.ccls. or 137/590.ccls. or 137/594-596.ccls. or 137/599.01.ccls. or 137/599.05-599.07.ccls. or 137/602.ccls.) or (141/285-286.ccls. or 141/37.ccls. or 141/44-47.ccls. or 141/54.ccls. or 141/301-302.ccls. or 141/367.ccls.) or (261/127.ccls. or 261/131.ccls. or 261/146-147.ccls. or 261/150.ccls.) or (261/19-22.ccls. or 261/23.1.ccls. or 261/40.ccls. or 261/42.ccls. or 261/62-63.ccls.) or (261/64.1.ccls. or 261/65.ccls. or 261/75-76.ccls. or 261/94-96.ccls. or 261/100-102.ccls. or 261/105.ccls. or 261/108-109.ccls. or 261/113.ccls. or 261/114.1.ccls.)) and (((injector or nozzle or sprayer or port or jet or "shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) with gas) same (stress or strain))) or (((("6197151") or ("6123775") or ("6079356") or ("5997649") or ("5968276") or ("5882411") or ("5846332") or ("5844205") or ("5647911") or ("5614026") or ("5582866") or ("5567243") or ("5439524") or ("4854263").PN.) or (((("6050216") or ("5882411") or ("5846332") or ("5778713") or ("5667631") or ("5597439") or ("5569356") or ("5472565") or ("5262029") or ("5074456") or ("4612077") or ("4585920") or ("4547247").PN.))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/29 11:27
7	2	us-20020069968-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/29 11:27
9	14	((("6197151") or ("6123775") or ("6079356") or ("5997649") or ("5968276") or ("5882411") or ("5846332") or ("5844205") or ("5647911") or ("5614026") or ("5582866") or ("5567243") or ("5439524") or ("4854263").PN.	USPAT	2003/12/22 09:04
10	73	((118/715.ccls. or 118/728.ccls. or 118/50.ccls. or 156/345.29.ccls. or 156/345.33.ccls. or 156/345.34.ccls. or 156/345.35.ccls. or 156/345.36.ccls. or 156/345.26.ccls. or 156/345.51.ccls.) or (137/262-264.ccls. or 137/454.2 or 137/560.ccls. or 137/561.ccls. or 137/561a.ccls. or 137/571-576.ccls. or 137/590.ccls. or 137/594-596.ccls. or 137/599.01.ccls. or 137/599.05-599.07.ccls. or 137/602.ccls.) or (141/285-286.ccls. or 141/37.ccls. or 141/44-47.ccls. or 141/54.ccls. or 141/301-302.ccls. or 141/367.ccls.) or (261/127.ccls. or 261/131.ccls. or 261/146-147.ccls. or 261/150.ccls.) or (261/19-22.ccls. or 261/23.1.ccls. or 261/40.ccls. or 261/42.ccls. or 261/62-63.ccls.) or (261/64.1.ccls. or 261/65.ccls. or 261/75-76.ccls. or 261/94-96.ccls. or 261/100-102.ccls. or 261/105.ccls. or 261/108-109.ccls. or 261/113.ccls. or 261/114.1.ccls.)) and (((injector or nozzle or sprayer or port or jet or "shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) with gas) same (stress or strain))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/22 09:43
11	2	6170432.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/22 09:29
12	13	((("6050216") or ("5882411") or ("5846332") or ("5778713") or ("5667631") or ("5597439") or ("5569356") or ("5472565") or ("5262029") or ("5074456") or ("4612077") or ("4585920") or ("4547247").PN.	USPAT	2003/12/22 09:35
13	4	"6,170,432"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/22 09:35

15	293	(wafer or substrate) and (((injector or nozzle or sprayer or port or jet or "shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) with gas)) same ((heat or thermal) with (stress or strain))) not (((118/715.ccls. or 118/728.ccls. or 118/50.ccls. or 156/345.29.ccls. or 156/345.33.ccls. or 156/345.34.ccls. or 156/345.35.ccls. or 156/345.36.ccls. or 156/345.26.ccls. or 156/345.51.ccls.) or (137/262-264.ccls. or 137/454.2 or 137/560.ccls. or 137/561.ccls. or 137/561a.ccls. or 137/571-576.ccls. or 137/590.ccls. or 137/594-596.ccls. or 137/599.01.ccls. or 137/599.05-599.07.ccls. or 137/602.ccls.) or (141/285-286.ccls. or 141/37.ccls. or 141/44-47.ccls. or 141/54.ccls. or 141/301-302.ccls. or 141/367.ccls.) or (261/127.ccls. or 261/131.ccls. or 261/146-147.ccls. or 261/150.ccls.) or (261/19-22.ccls. or 261/23.1.ccls. or 261/40.ccls. or 261/42.ccls. or 261/62-63.ccls.) or (261/64.1.ccls. or 261/65.ccls. or 261/75-76.ccls. or 261/94-96.ccls. or 261/100-102.ccls. or 261/105.ccls. or 261/108-109.ccls. or 261/113.ccls. or 261/114.1.ccls.)) and (((injector or nozzle or sprayer or port or jet or "shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) with gas) same (stress or strain))) or (((("6197151") or ("6123775") or ("6079356") or ("5997649") or ("5968276") or ("5882411") or ("5846332") or ("5844205") or ("5647911") or ("5614026") or ("5582866") or ("5567243") or ("5439524") or ("4854263").PN.) or (((6050216") or ("5882411") or ("5846332") or ("5778713") or ("5667631") or ("5597439") or ("5569356") or ("5472565") or ("5262029") or ("5074456") or ("4612077") or ("4585920") or ("4547247").PN.))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/29 11:27
16	5318	(wafer or substrate) and ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) same (heat or thermal) with (stress or strain))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/29 11:30
17	107	(wafer or substrate) and ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) same (heat or thermal) with (stress or strain)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/29 11:34
18	7364	(wafer or substrate) and ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) and (heat or thermal) with (stress or strain)) and plasma	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/29 11:35
19	7364	(wafer or substrate) and ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) and ((heat or thermal) with (stress or strain)) and plasma	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/29 11:48
20	3188	(wafer or substrate) and ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) with (stress or strain)) and plasma	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/29 11:36
21	180	(wafer or substrate) and ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) with (stress or strain)).clm. and plasma	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/29 11:36
22	27702	(wafer or substrate) and ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) and (heat or thermal) and (stress or strain) and plasma not ((wafer or substrate) and ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) with (stress or strain)).clm. and plasma)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/29 11:49

23	8437	((wafer or substrate) same (reactor or chamber or vessel or tank or station or hous\$3 or encase\$4 or container or ampoule)) and ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) and (heat or thermal) and (stress or strain) and plasma not ((wafer or substrate) and ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) with (stress or strain)).clm. and plasma)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/29 11:50
24	2791	((((wafer or substrate) same (reactor or chamber or vessel or tank or station or hous\$3 or encase\$4 or container or ampoule)) same ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) and (heat or thermal) and (stress or strain) and plasma not ((wafer or substrate) and ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) with (stress or strain)).clm. and plasma)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/29 11:51
25	100	((((wafer or substrate) same (reactor or chamber or vessel or tank or station or hous\$3 or encase\$4 or container or ampoule)) same ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) and (heat or thermal).clm. and (stress or strain).clm. and plasma not ((wafer or substrate) and ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) with (stress or strain)).clm. and plasma)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/29 12:13
26	2691	((((wafer or substrate) same (reactor or chamber or vessel or tank or station or hous\$3 or encase\$4 or container or ampoule)) same ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) and (heat or thermal) and (stress or strain) and plasma not (((wafer or substrate) and ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) with (stress or strain)).clm. and plasma) or (((wafer or substrate) same (reactor or chamber or vessel or tank or station or hous\$3 or encase\$4 or container or ampoule)) same ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) and (heat or thermal).clm. and (stress or strain).clm. and plasma not ((wafer or substrate) and ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) with (stress or strain)).clm. and plasma)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/29 12:15
27	1409	((((wafer or substrate) same (reactor or chamber or vessel or tank or station or hous\$3 or encase\$4 or container or ampoule)) same ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) and (heat or thermal) same (stress or strain)) and plasma not (((wafer or substrate) and ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) with (stress or strain)).clm. and plasma) or (((wafer or substrate) same (reactor or chamber or vessel or tank or station or hous\$3 or encase\$4 or container or ampoule)) same ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) and (heat or thermal).clm. and (stress or strain).clm. and plasma not ((wafer or substrate) and ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) with (stress or strain)).clm. and plasma)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/29 12:16
28	1376	((((wafer or substrate) same (reactor or chamber or vessel or tank or station or hous\$3 or encase\$4 or container or ampoule)) same ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) and (heat or thermal) same (stress or strain)) and plasma not (((wafer or substrate) and ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) with (stress or strain)).clm. and plasma) or (((wafer or substrate) same (reactor or chamber or vessel or tank or station or hous\$3 or encase\$4 or container or ampoule)) same ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) and (heat or thermal).clm. and (stress or strain).clm. and plasma not ((wafer or substrate) and ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) with (stress or strain)).clm. and plasma) or blood)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/29 12:16

29	1096	(((wafer or substrate) same (reactor or chamber or vessel or tank or station or hous\$3 or encase\$4 or container or ampoule)) same ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3)) and ((heat or thermal) same (stress or strain)) and plasma not (((wafer or substrate) and ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) with (stress or strain)).clm. and plasma) or (((wafer or substrate) same (reactor or chamber or vessel or tank or station or hous\$3 or encase\$4 or container or ampoule)) same ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3)) and (heat or thermal).clm. and (stress or strain).clm. and plasma not ((wafer or substrate) and ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) with (stress or strain)).clm. and plasma) or blood)) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/29 12:16
30	574	(((wafer or substrate) same (reactor or chamber or vessel or tank or station or hous\$3 or encase\$4 or container or ampoule)) same ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3)) and ((heat or thermal) same (stress or strain)) and plasma not (((wafer or substrate) and ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) with (stress or strain)).clm. and plasma) or (((wafer or substrate) same (reactor or chamber or vessel or tank or station or hous\$3 or encase\$4 or container or ampoule)) same ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3)) and (heat or thermal).clm. and (stress or strain).clm. and plasma not ((wafer or substrate) and ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) with (stress or strain)).clm. and plasma) or blood)) and semiconductor) and ((expand\$3 or expansion) with (heat or thermal))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/29 13:43
31	2	6477980.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/29 13:47
32	70	((wafer or substrate) and ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) and (heat or thermal) and (stress or strain) and plasma not ((wafer or substrate) and ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) with (stress or strain)).clm. and plasma) and (427/446.ccls. or 427/457.ccls. or 29/746.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/29 13:51